

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-22. (Canceled)

23. (Currently amended) ~~The EMI/RFI shielding device of claim 21~~An EMI/RFI shielding device comprising:

a shaped polymer substrate comprised of a metallized polymer substrate, wherein the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate;

wherein the shaped polymer substrate comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol.

24. (Currently amended) ~~The EMI/RFI shielding device of claim 21~~An EMI/RFI shielding device comprising:

a shaped polymer substrate comprised of a metallized polymer substrate, wherein the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate;

wherein the conductive material has a thickness between 1.0 micron and 50.0 microns.

25. (Currently amended) The EMI/RFI shielding device of claim 24 23 wherein the conductive material comprises aluminum.

26. (Currently amended) The EMI/RFI shielding device of claim 24 23 wherein the conductive material comprises a substantially uniform thickness over at least one surface of the shaped polymer substrate.

27. (Currently amended) ~~The EMI/RFI shielding device of claim 21 An~~
EMI/RFI shielding device comprising:

a shaped polymer substrate comprised of a metallized polymer substrate, wherein
the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate;

wherein the shaped polymer substrate has a thickness between 0.006 inches to
0.100 inches.

28. (Currently amended) ~~The EMI/RFI shielding device of claim 21 An~~
EMI/RFI shielding device comprising:

a shaped polymer substrate comprised of a metallized polymer substrate, wherein
the shaped polymer substrate is substantially conductive; and

a conductive material on at least one surface of the shaped polymer substrate;

wherein the shaped polymer substrate comprises:

a first surface;

a plurality of sidewalls that comprise a first end and a second end, wherein a first
end of each of the sidewalls are coupled to the first surface, wherein the sidewalls extend at an
angle from the first surface, wherein the first surface and sidewalls define an enclosure portion;
and

a peripheral flange coupled to the second end of the sidewalls that extends around
the enclosure portion.

29. (Previously presented) An EMI/RFI shield comprising:
a thermoformed thin-walled shape formed of a recycled metallized polymeric material, wherein the thermoformed thin-walled shape comprises an inner surface, an outer surface and edges; and

a conductive material deposited on at least one of the inner surface and outer surface, wherein the conductive coating comprises a substantially even thickness between 1 micron to 50 microns.

30. (Previously presented) The EMI/RFI shield of claim 29 wherein the conductive material comprises vacuum deposited aluminum.

31. (Previously presented) The EMI/RFI shield of claim 29 wherein the recycled metallized polymeric material comprises a reground and re-extruded metal layer and a polymeric material.

32. (Previously presented) The EMI/RFI shield of claim 29 wherein the polymeric material comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol.

33. (Previously presented) The EMI/RFI shield of claim 29 wherein the thermoformed thin-walled shape has a thickness between 0.006 inches to 0.100 inches.

34. (Previously presented) The EMI/RFI shield of claim 29 wherein the thermoformed thin-walled shape comprises:

a first surface;

a plurality of sidewalls that comprise a first end and a second end, wherein a first end is coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion; and

a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion.

35-45. (Canceled)

46. (Currently amended) The EMI/RFI shielding device of claim 21 23 further comprising grinding and re-extruding a metal material along with the polymer substrate.

47-48. (Canceled)

49. (Currently amended) The EMI/RFI shielding device of claim 21 23 wherein the conductive material comprises copper.

50. (Currently amended) The EMI/RFI shielding device of claim 21 23 wherein the conductive material comprises nickel.

51. (Previously presented) The EMI/RFI shield of claim 29 wherein the conductive material comprises vacuum deposited copper.

52. (Previously presented) The EMI/RFI shield of claim 29 wherein the conductive material comprises vacuum deposited nickel.